



NOTES:  
 1) MATERIAL:  
 HOUSING: HI-TEMP. PLASTIC UL 94V-0  
 CONTACT: COPPER ALLOY  
 SHELL: STAINLESS STEEL  
 2) FINISH:  
 CONTACT: GOLD PLATED ON CONTACT AREA;  
 GOLD FLASH PLATED ON SOLDER TAILS,  
 SHELL: NICKEL UNDERPLATED OVERALL,  
 GOLD FLASH PLATED ON SOLDER TAILS

RECOMMENDED PCB LAYOUT(TOP VIEW)  
 GENERAL TOLERANCES: ±0.05

▨ PAD AREA

SIM CARD PIN NO.	PIN NAME	MICRO SIM CARD PIN NO.	PIN NAME	SIM CARD PIN NO.	PIN NAME
T1	DAT2	C1	VCC	C1	VCC
T2	CD/DAT3	C2	RST	C2	RST
T3	CMD	C3	CLK	C3	CLK
T4	VDD	C5	GND	C5	GND
T5	CLK	C6	VPP	C6	VPP
T6	VSS	C7	I/O	C7	I/O
T7	DATO	SHELL NAIL PIN NO.		PIN NAME	
T8	DAT1	G1~G4		GROUND	

GENERAL TOLERANCE	图号	JYSA1504-001	设计	Raliny.xu	比例	1:1
X.±0.35	X.±5'	3 IN 1 CARD CONN.	设计		单位	mm
X±0.25	X.±2'	SMT TYPE 2.50H	审核		视角	AO
.XX±0.15	.XX±1'	料号	日期	2015/03/16	版本	AO
.XXX±0.05	.xxx'±0.5'					

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REV.	ECN.NO.	MODIFY/CONTENT	DATE
B		MODIFY	2015/04/11